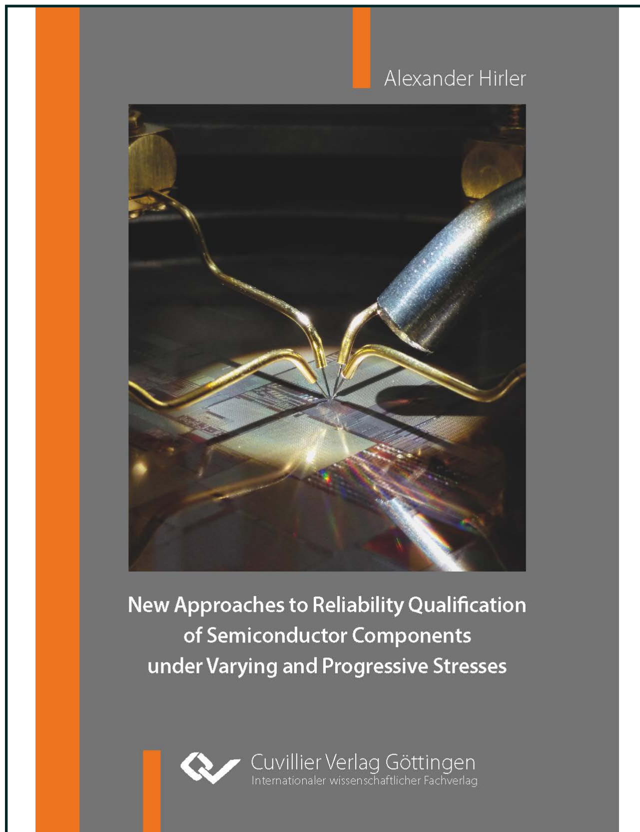
Alexander Hirler (Autor)

New Approaches to Reliability Qualification of Semiconductor Components under Varying and Progressive Stresses



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